



Package Bill of Material Change for Spartan-3AN Wire Bond Package

XCN17001 (v1.0) March 6, 2017

Product Change Notice – For Information Only

Overview

The purpose of this notification is to announce the change of die attach film on wire bond packages for “XC” commercial (C), industrial (I) grade Spartan®-3AN products.

Description

Xilinx material supplier Nitto will discontinue supply of specific die attach film in March 2017 due to its raw material’s supplier ending business. Xilinx has successfully qualified Hitachi’s new die attach film in mass production for past 3 years without any quality or reliability issues. This change is aligning the die attach film to industry best practice and enables supply continuity for commercial and industrial “XC” Spartan-3AN products in wire bond packages. This change will not affect fit, form, function, reliability or MSL rating of the packages.

Products Affected

This change affects all speed, package, and temperature grade of “XC” commercial (C), industrial (I) products listed in the [Table 1](#)

Table 1: Spartan-3AN FPGAs XC Devices Packages Affected

Device-Package	Device-Package	Device-Package
XC3S400AN-FT(G)256	XC3S1400AN-FG(G)676	XC3S700AN-FG(G)484
XC3S200AN-FT(G)256	XC3S400AN-FG(G)400	XC3S50AN-TQ(G)144

Key Dates and Ordering Information

Xilinx will begin cross shipping products using current and new die attach film upon release of this PCN.

Qualification Data

Qualification data per RPT234 is available upon request.

Response

No response is expected. For additional information or questions, please contact [Xilinx Technical Support](#).

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Additional Documentation

[XTP457](#) – FAQ: Implications of XCN17001

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/06/2017	1.0	Initial release.

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